

BS EN 61190-1-2:2014



BSI Standards Publication

Attachment materials for electronic assembly

Part 1-2: Requirements for soldering
pastes for high-quality interconnects
in electronics assembly

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National foreword

This British Standard is the UK implementation of EN 61190-1-2:2014. It is identical to IEC 61190-1-2:2014. It supersedes BS EN 61190-1-2:2007 which is withdrawn.

The UK participation in its preparation was entrusted to Technical Committee EPL/501, Electronic assembly technology & Printed Electronics.

A list of organizations represented on this committee can be obtained on request to its secretary.

This publication does not purport to include all the necessary provisions of a contract. Users are responsible for its correct application.

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Amendments/corrigenda issued since publication

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